

SOD523V

plastic surface-mounted package; 2 leads

8 February 2016

Package information

1. Package summary

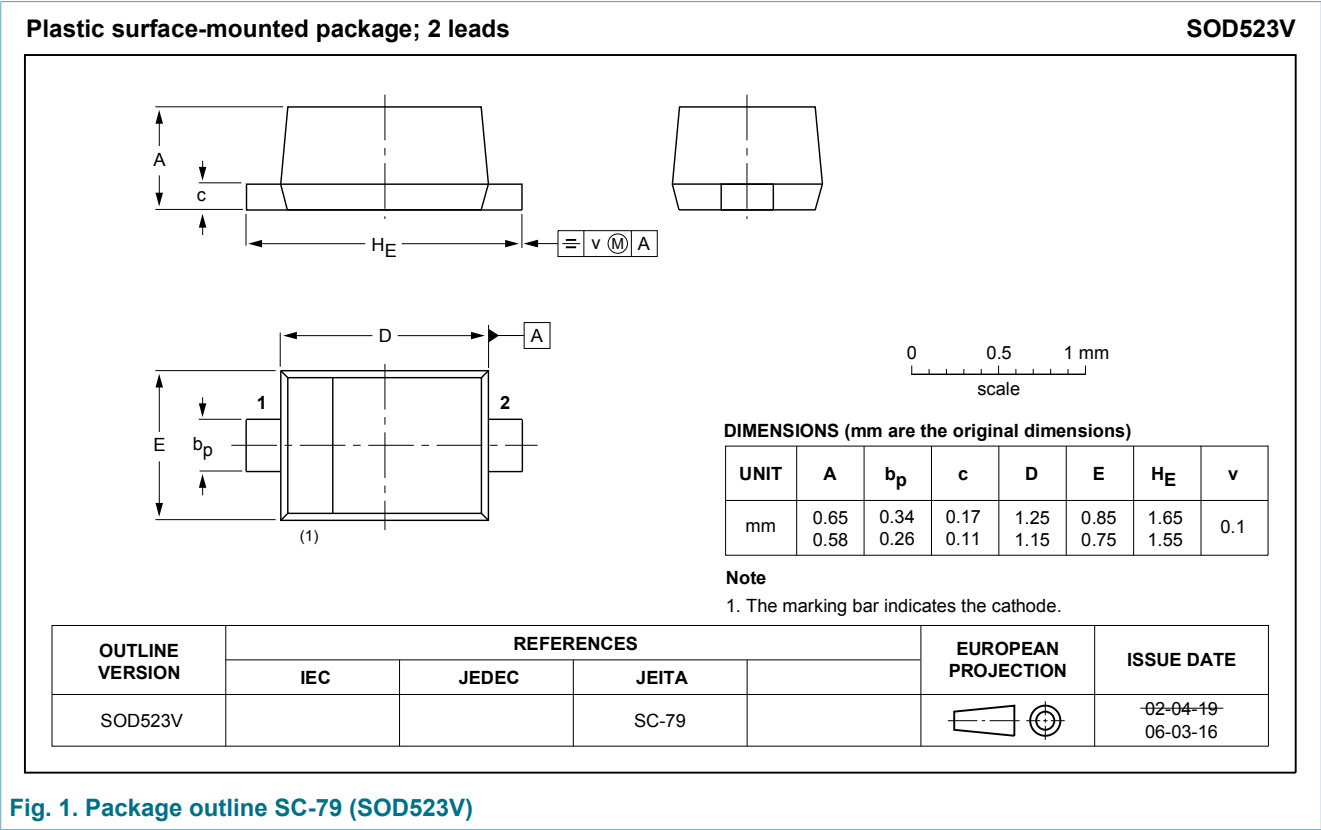
Terminal position code	D (double)
Package type descriptive code	SC-79
Package type industry code	SC-79
Package style descriptive code	SOD (small outline diode)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEITA package outline code	SC-79
Mounting method type	S (surface mount)
Issue date	16-3-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.15	-	1.2	1.25	mm
E	package width		0.75	-	0.8	0.85	mm
A	seated height		0.58	-	0.65	0.65	mm
n ₂	actual quantity of termination		-	-	2	-	



2. Package outline



3. Legal information

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